# LN2162C68TR

Surface Mounting Chip LED

#### GW Bi-Color Type

### Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol Rating		Unit
Power dissipation	P <sub>D</sub>	45	mW
Forward current	I <sub>F</sub>	15	mA
Pulse forward current *	I <sub>FP</sub>	60	mA
Reverse voltage	V <sub>R</sub>	3	v
Operating ambient temperature	T <sub>opr</sub>	-25 to +80	°C
Storage temperature	T <sub>stg</sub>	-30 to +85	°C

Note) \*: The condition of  $I_{FP}$  is duty 10%, Pulse width 1 msec.

#### • Orange

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Note) \*: The condition of  $I_{FP}$  is duty 10%, Pulse width 1 msec.

#### Electro-Optical Characteristics $T_a = 25^{\circ}C$

Pure	Green
	Pure

Parameter		Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity		Io	"THE	1.2	2.5		mcd
Forward current		Nº IF	5		10		mA
Forward voltage	1.0	V <sub>F</sub>	$I_{\rm F} = 10  {\rm mA}$		2.05	2.8	V
Peak emission wavelength	24	$\lambda_{\rm P}$	$I_F = 10 \text{ mA}$		555		nm
Spectral half band width	aller	Δλ	$I_{\rm F} = 10  {\rm mA}$		25		nm
Reverse current	64	I <sub>R</sub>	$V_R = 3 V$			10	μΑ

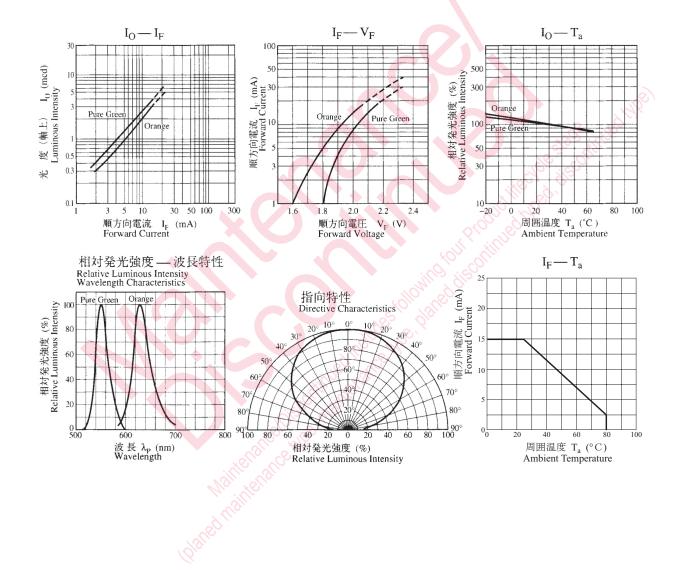
#### Lighting Color / Lens Color

- Pure Green / Clear
- Orange / Clear

#### Electro-Optical Characteristics (Continued) $T_a = 25^{\circ}C$

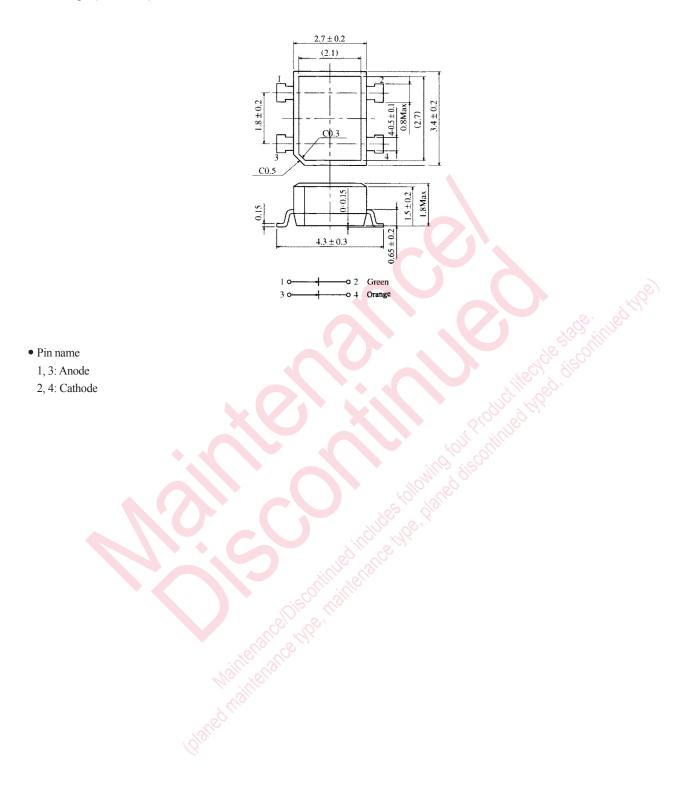
• Orange

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity	I <sub>O</sub>		0.8	2.1		mcd
Forward current	$I_{\rm F}$			10		mA
Forward voltage	V <sub>F</sub>	$I_{\rm F} = 10 \text{ mA}$		1.95	2.8	V
Peak emission wavelength	$\lambda_{\mathrm{P}}$	$I_{\rm F} = 10 \text{ mA}$		630		nm
Spectral half band width	Δλ	$I_{\rm F} = 10 \text{ mA}$		40		nm
Reverse current	I <sub>R</sub>	$V_R = 3 V$			10	μΑ



### **Panasonic**

Package (Unit: mm)



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